

Memory Module Specifications

HX324C11T2K2/8

8GB (4GB 512M x 64-Bit x 2 pcs.)
 DDR3-2400 CL11 240-Pin DIMM Kit



DESCRIPTION

HyperX HX324C11T2K2/8 is a kit of two 512M x 64-bit (4GB) DDR3-2400 CL11 SDRAM (Synchronous DRAM), 1Rx8 memory modules, based on eight 512M x 8-bit FBGA components per module. Each module kit supports Intel® XMP (Extreme Memory Profiles). Total kit capacity is 8GB. Each module kit has been tested to run at DDR3-2400 at a low latency timing of 11-13-14 at 1.65V. The SPDs are programmed to JEDEC standard latency DDR3-1600 timing of 11-11-11 at 1.5V. Each 240-pin DIMM uses gold contact fingers. The JEDEC standard electrical and mechanical specifications are as follows:

XMP TIMING PARAMETERS

- JEDEC: DDR3-1600 CL11-11-11 @1.5V
- XMP Profile #1: DDR3-2400 CL11-13-14 @1.65V
- XMP Profile #2: DDR3-2133 CL11-13-13 @1.6V

SPECIFICATIONS

CL(IDD)	11 cycles
Row Cycle Time (tRCmin)	48.125ns(min.)
Refresh to Active/Refresh Command Time (tRFCmin)	260ns(min.)
Row Active Time (tRASmin)	35ns(min.)
Maximum Operating Power	TBD W*
UL Rating	94 V - 0
Operating Temperature	0° C to +85° C
Storage Temperature	-55° C to +100° C

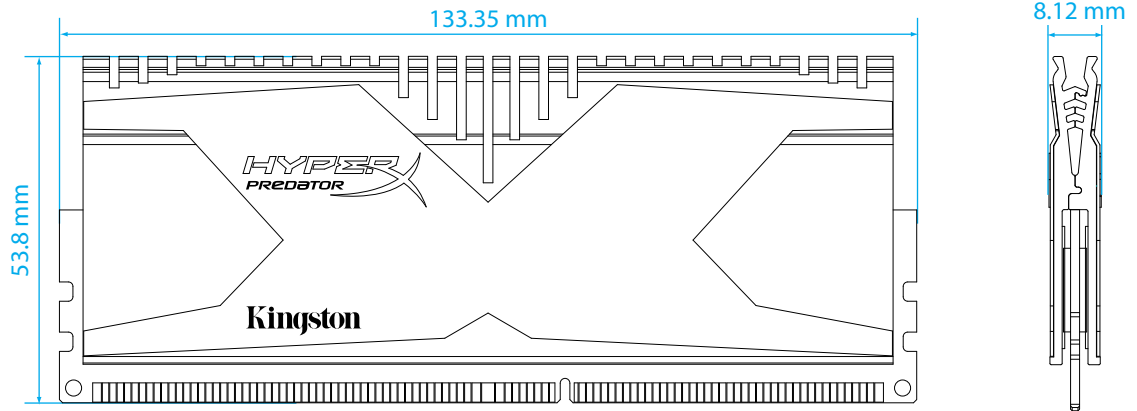
*Power will vary depending on the SDRAM used.

FEATURES

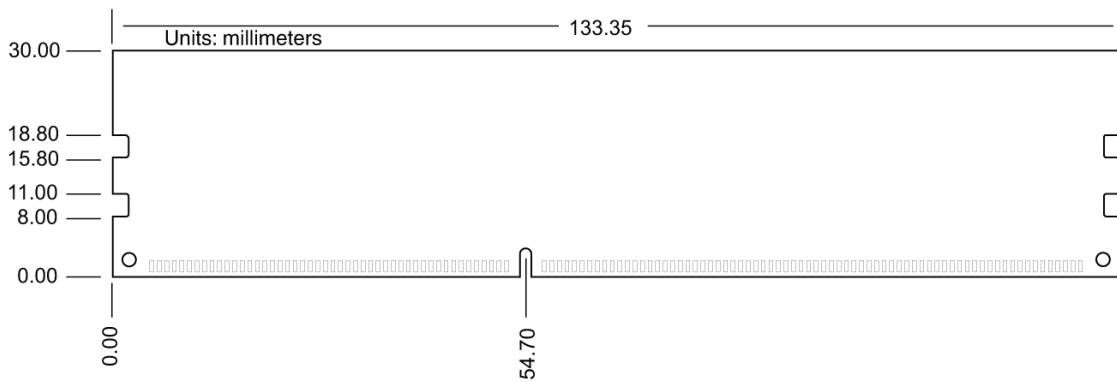
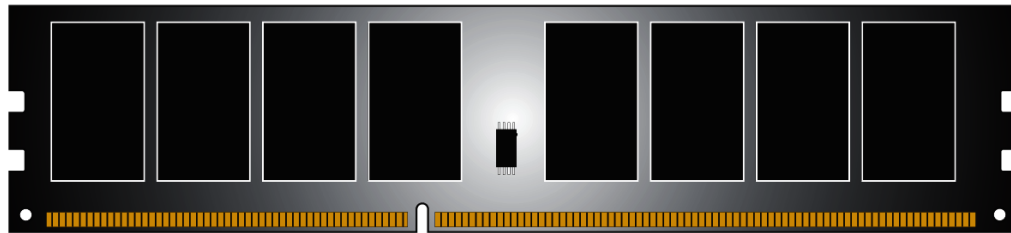
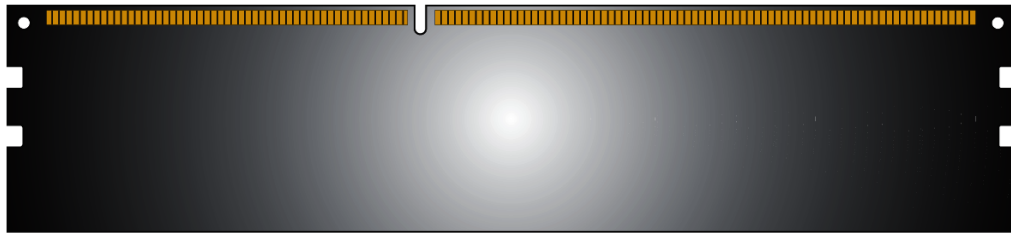
- JEDEC standard 1.5V (1.425V ~ 1.575V) Power Supply
- VDDQ = 1.5V (1.425V ~ 1.575V)
- 800MHz fCK for 1600Mb/sec/pin
- 8 independent internal banks
- Programmable CAS latency: 11, 10, 9, 8, 7, 6
- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- 8-bit pre-fetch
- Burst Length: 8 (interleave without any limit, sequential with starting address "000" only), 4 with tCCD = 4 which does not allow seamless read or write (either on the fly using A12 or MRS)
- Bi-directional Differential Data Strobe
- Internal (self) calibration: Internal self calibration through ZQ pin (RZQ: 240 ohm ± 1%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8us at lower than TCASE 85°C, 3.9us at 85°C < TCASE < 95°C°
- Asynchronous Reset
- Height 2.118" (53.80mm), w/heatsink, single sided component

Continued >>

MODULE WITH HEAT SPREADER



MODULE DIMENSIONS



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